

# HML60N105E7

## N-Channel eMOS E7 Power MOSFET

600 V, 31 A, 105 mΩ

### Description

The 600V eMOS E7 is an advanced Power Master Semiconductor's Super Junction MOSFET family by utilizing charge balance technology for excellent low on-resistance and gate charge. This technology combines the benefits of a fast switching performance with ease of usage and robustness. Consequently, the eMOS E7 family is suitable for application requiring high power density and superior efficiency.

PQFN88 Kelvin source configuration package offers excellent switching performance thanks to separated power and drive sources for high efficiency and high switching frequency applications.

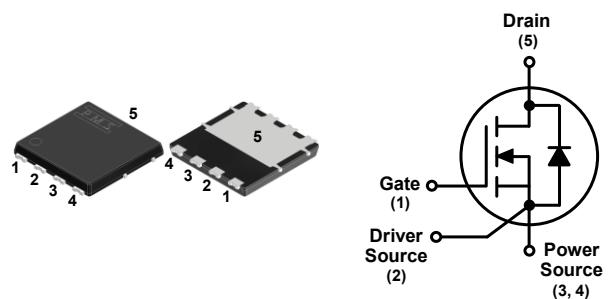
### Applications

- PFC, Hard & Soft Switching Topologies
- Industrial & Consumer Power Supplies

### Features

$BV_{DSS}$ @ $T_{J,max}$	$I_D$	$R_{DS(on),max}$	$Q_{g,typ}$
650 V	31 A	105 mΩ	52 nC

- Reduced Switching & Conduction Losses
- Lower Gate Resistance
- 100% Avalanche Tested
- Pb-free, Halogen Free, RoHS and MSL2a Compliant



### Absolute Maximum Ratings ( $T_C = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter		Value	Unit
$V_{DSS}$	Drain to Source Voltage		600	V
$V_{GSS}$	Gate to Source Voltage		$\pm 30$	V
$I_D$	Drain Current	Continuous ( $T_C = 25^\circ\text{C}$ )	31	A
		Continuous ( $T_C = 100^\circ\text{C}$ )	19.6	
$I_{DM}$	Drain Current	Pulsed (Note1)	93	A
$E_{AS}$	Single Pulsed Avalanche Energy		(Note2)	199 mJ
$I_{AS}$	Avalanche Current		(Note2)	5.6 A
$E_{AR}$	Repetitive Avalanche Energy		(Note1)	2.6 mJ
$dv/dt$	MOSFET $dv/dt$		100	V/ns
	Peak Diode Recovery $dv/dt$		(Note3)	
$P_D$	Power Dissipation	( $T_C = 25^\circ\text{C}$ )	260	W
		Derate Above 25°C	2.08	
$T_J, T_{STG}$	Operating and Storage Temperature Range		-55 to 150	°C
$T_L$	Maximum Lead Temperature for Soldering		260	°C

### Thermal Characteristics

Symbol	Parameter	Value	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	0.48	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max. (Note4)	45	

**Package Marking and Ordering Information**

Part Number	Top Marking	Package	Packing Method	Quantity
HML60N105E7	HML60N105E7	PQFN88	Tape & Reel	3000 units

**Electrical Characteristics ( $T_C = 25^\circ\text{C}$  unless otherwise noted)**

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
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**Off Characteristics**

$\text{BV}_{\text{DSS}}$	Drain to Source Breakdown Voltage	$V_{\text{GS}} = 0 \text{ V}, I_D = 1 \text{ mA}$	600			V
		$V_{\text{GS}} = 0 \text{ V}, I_D = 1 \text{ mA}, T_J = 150^\circ\text{C}$	650			
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{\text{DS}} = 600 \text{ V}, V_{\text{GS}} = 0 \text{ V}$			1	$\mu\text{A}$
		$V_{\text{DS}} = 480 \text{ V}, V_{\text{GS}} = 0 \text{ V}, T_J = 125^\circ\text{C}$		2.1		
$I_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}} = \pm 30 \text{ V}, V_{\text{DS}} = 0 \text{ V}$			$\pm 100$	nA

**On Characteristics**

$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}} = V_{\text{DS}}, I_D = 2.1 \text{ mA}$	2.5		4.5	V
$R_{\text{DS(on)}}$	Static Drain to Source On Resistance	$V_{\text{GS}} = 10 \text{ V}, I_D = 11.5 \text{ A}$		89	105	$\text{m}\Omega$

**Dynamic Characteristics**

$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}} = 400 \text{ V}, V_{\text{GS}} = 0 \text{ V}, f = 250 \text{ kHz}$		2270		pF
$C_{\text{oss}}$	Output Capacitance		58			pF
$C_{\text{o(tr)}}$	Time Related Output Capacitance	$V_{\text{DS}} = 0 \text{ V to } 400 \text{ V}, V_{\text{GS}} = 0 \text{ V}$		670		pF
$C_{\text{o(er)}}$	Energy Related Output Capacitance		92			pF
$Q_{\text{g(tot)}}$	Total Gate Charge at 10 V	$V_{\text{DS}} = 400 \text{ V}, I_D = 15.3 \text{ A}, V_{\text{GS}} = 10 \text{ V}$		52		nC
$Q_{\text{gs}}$	Gate to Source Charge			12.7		nC
$Q_{\text{gd}}$	Gate to Drain "Miller" Charge			22.4		nC
$R_G$	Gate Resistance	$f = 1 \text{ MHz}$		0.9		$\Omega$

**Switching Characteristics**

$t_{\text{d(on)}}$	Turn-On Delay Time	$V_{\text{DS}} = 400 \text{ V}, I_D = 15.3 \text{ A}, V_{\text{GS}} = 10 \text{ V}, R_G = 10 \Omega$ See Figure 13		18		ns
$t_r$	Turn-On Rise Time			9		ns
$t_{\text{d(off)}}$	Turn-Off Delay Time			83		ns
$t_f$	Turn-Off Fall Time			7		ns

**Source-Drain Diode Characteristics**

$I_S$	Maximum Continuous Diode Forward Current			31	A	
$I_{\text{SM}}$	Maximum Pulsed Diode Forward Current			93	A	
$V_{\text{SD}}$	Diode Forward Voltage	$V_{\text{GS}} = 0 \text{ V}, I_{\text{SD}} = 15.3 \text{ A}$		1.2	V	
$t_{\text{rr}}$	Reverse Recovery Time	$V_{\text{DD}} = 400 \text{ V}, I_{\text{SD}} = 15.3 \text{ A}, dI_F/dt = 100 \text{ A}/\mu\text{s}$		346		ns
$Q_{\text{rr}}$	Reverse Recovery Charge			5.1		$\mu\text{C}$

※Notes:

- Repetitive rating: pulse-width limited by maximum junction temperature.
- $I_{\text{AS}} = 5.6 \text{ A}, R_G = 25 \Omega$ , starting  $T_J = 25^\circ\text{C}$ .
- $I_{\text{SD}} \leq 15.3 \text{ A}, di/dt \leq 100 \text{ A}/\mu\text{s}, V_{\text{DD}} \leq 400 \text{ V}$ , starting  $T_J = 25^\circ\text{C}$ .
- Device on 1.0 x 1.0 inch and 2-oz copper pad on 1.5 x 1.5 inch PCB FR4.

## Typical Performance Characteristics

Figure 1. On-Region Characteristics

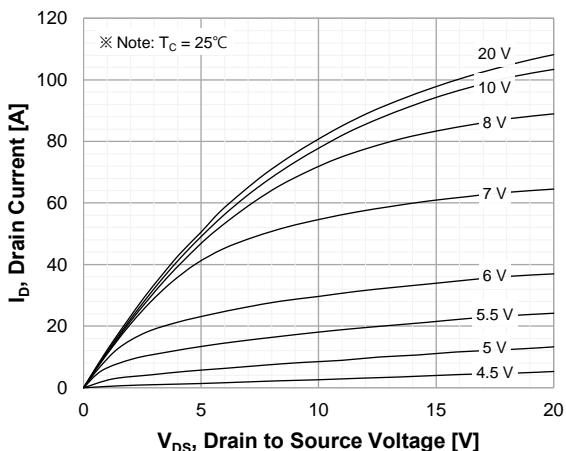


Figure 2. Transfer Characteristics

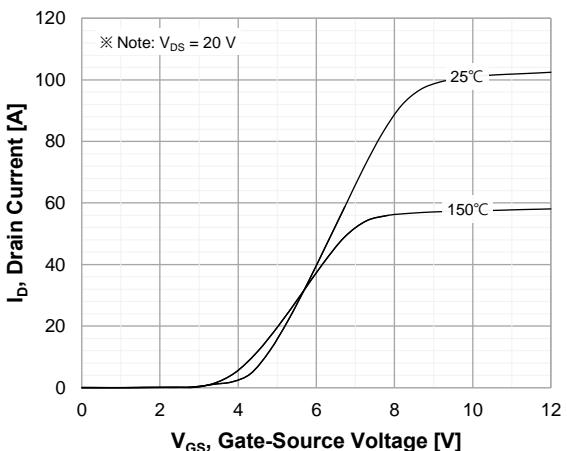


Figure 3. On-Resistance Characteristics vs. Drain Current and Gate Voltage

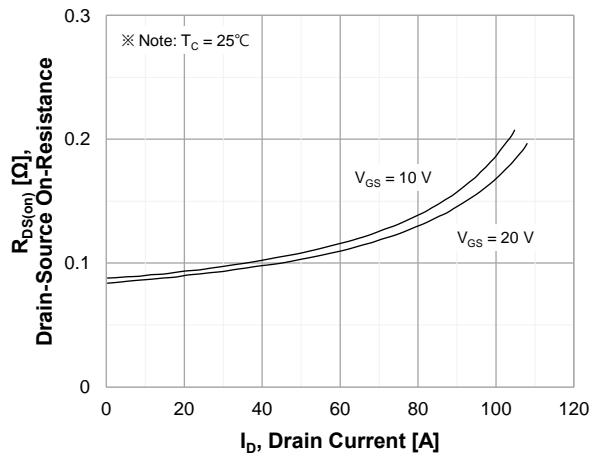


Figure 4. Diode Forward Voltage Characteristics vs. Source-Drain Current and Temperature

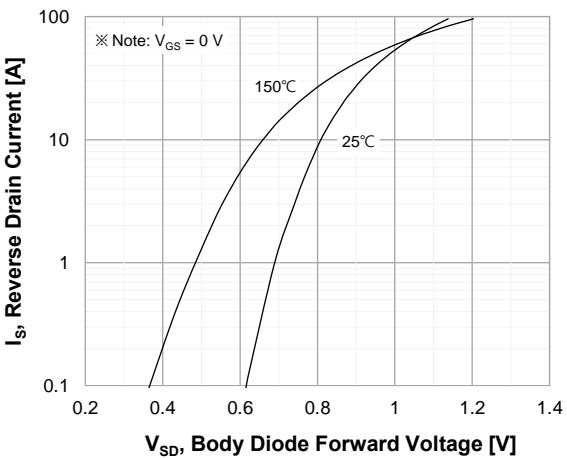


Figure 5. Capacitance Characteristics

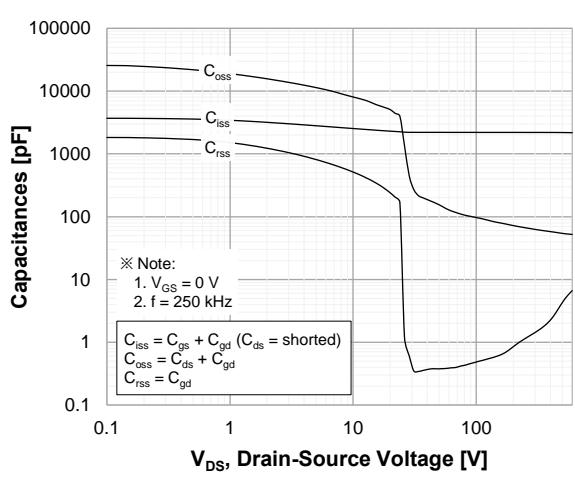
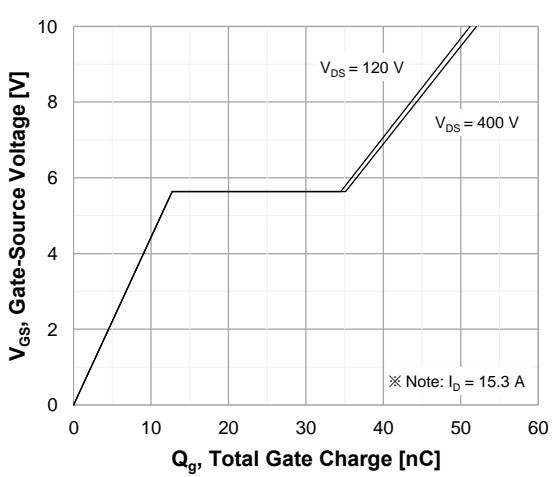
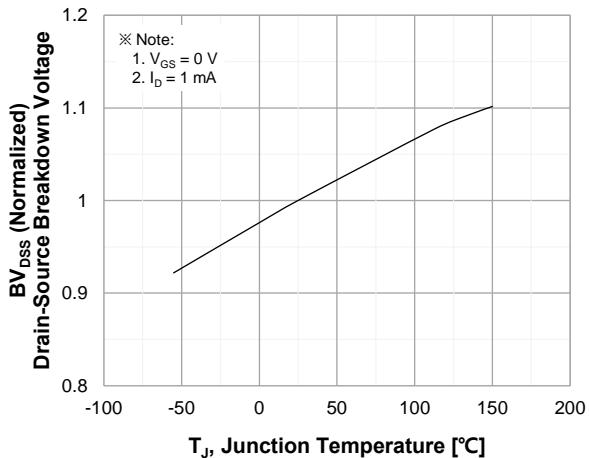


Figure 6. Gate Charge Characteristics

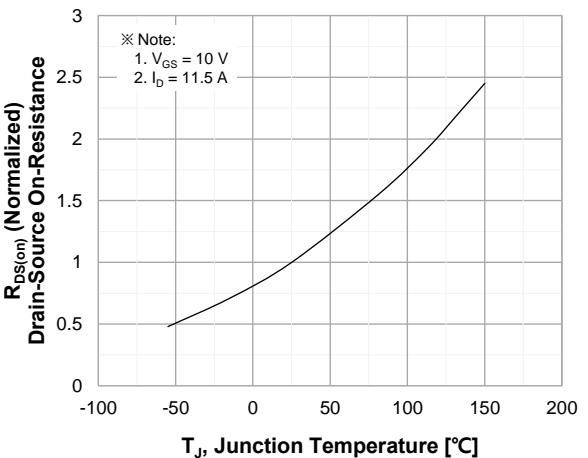


### Typical Performance Characteristics

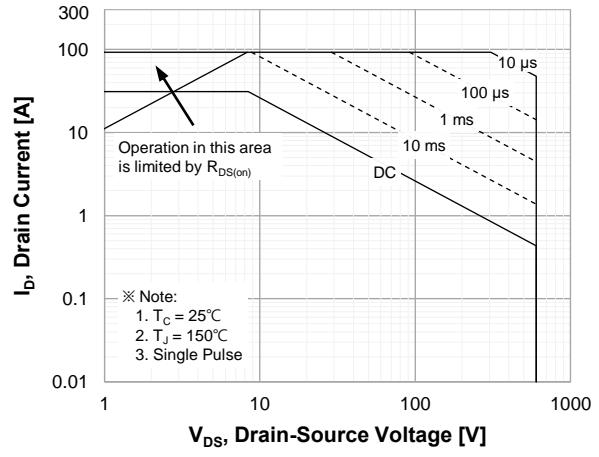
**Figure 7. Breakdown Voltage Characteristics vs. Temperature**



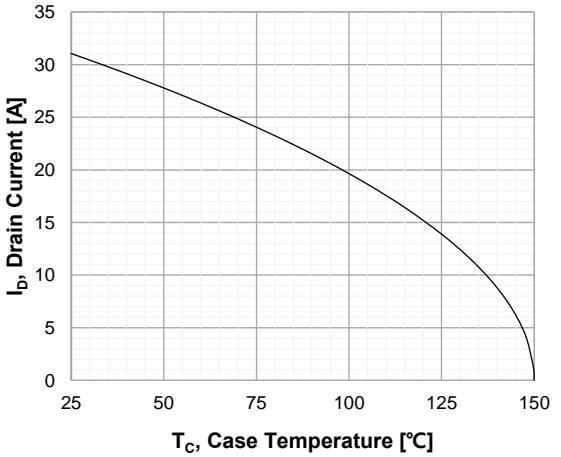
**Figure 8. On-Resistance Characteristics vs. Temperature**



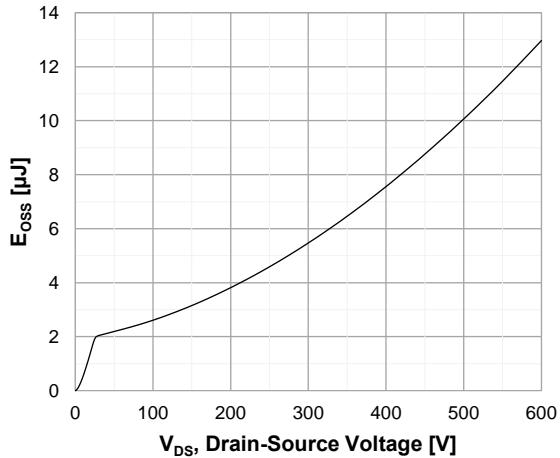
**Figure 9. Maximum Safe Operating Area**



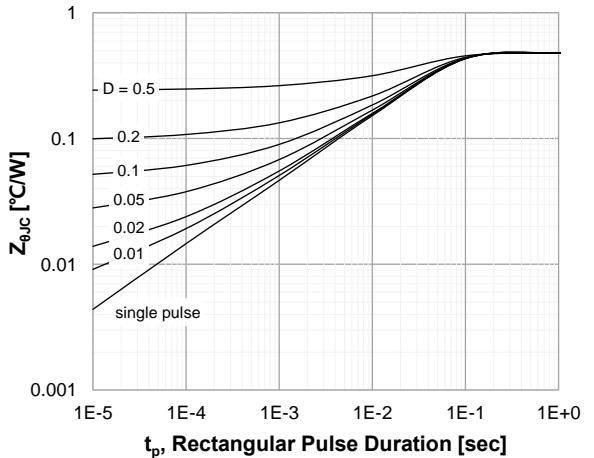
**Figure 10. Maximum Drain Current vs. Case Temperature**



**Figure 11.  $E_{oss}$  vs. Drain to Source Voltage**

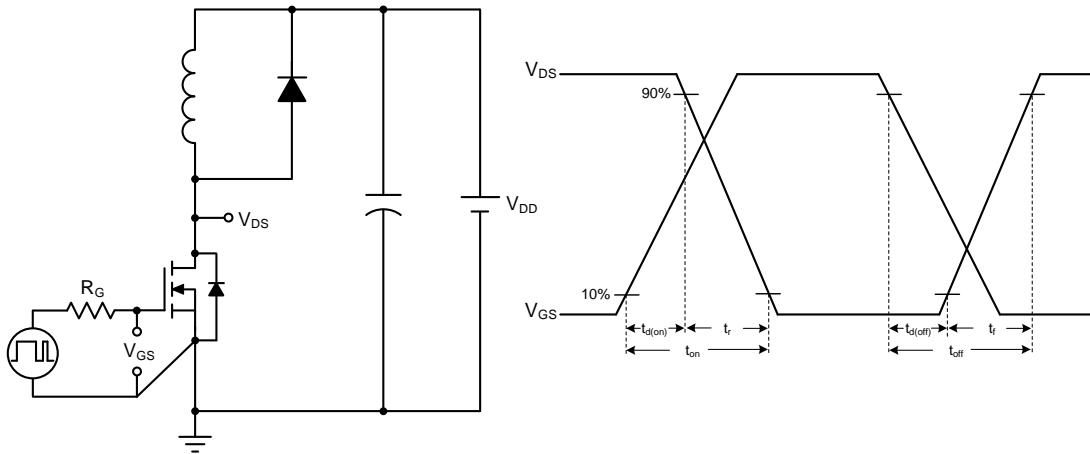


**Figure 12. Transient Thermal Response Curve**

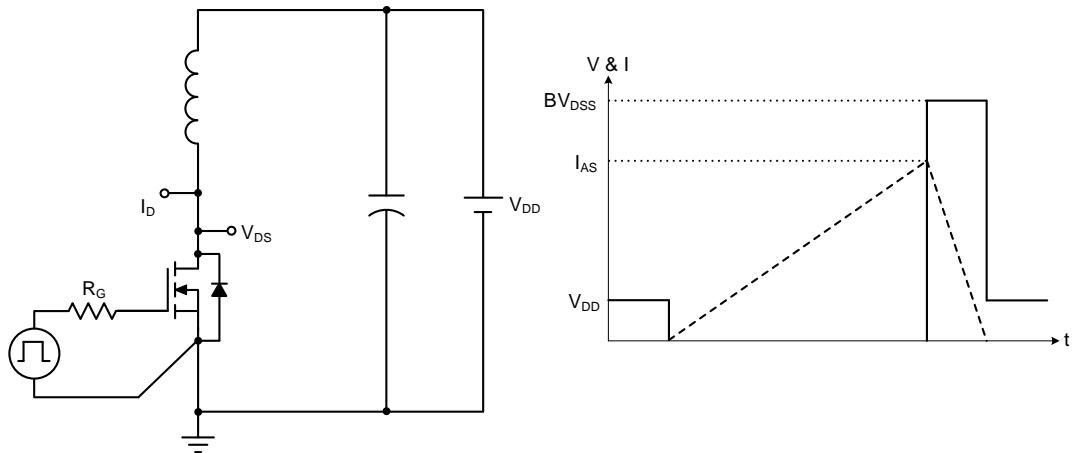


## Test Circuits

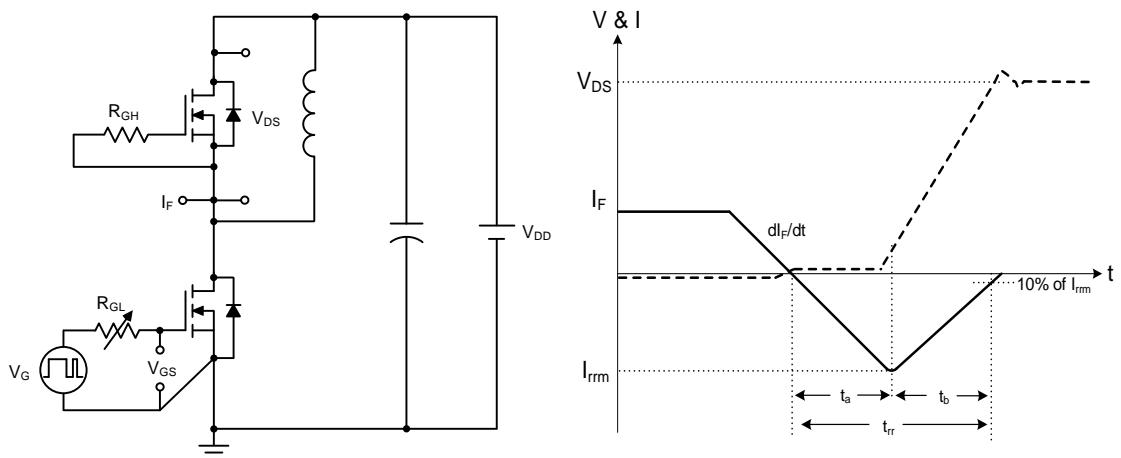
**Figure 13. Inductive Load Switching Test Circuit and Waveforms**



**Figure 14. Unclamped Inductive Switching Test Circuit and Waveforms**

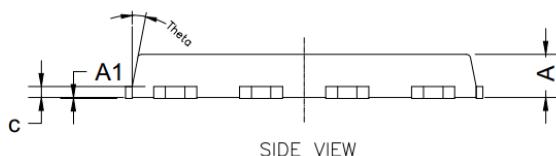
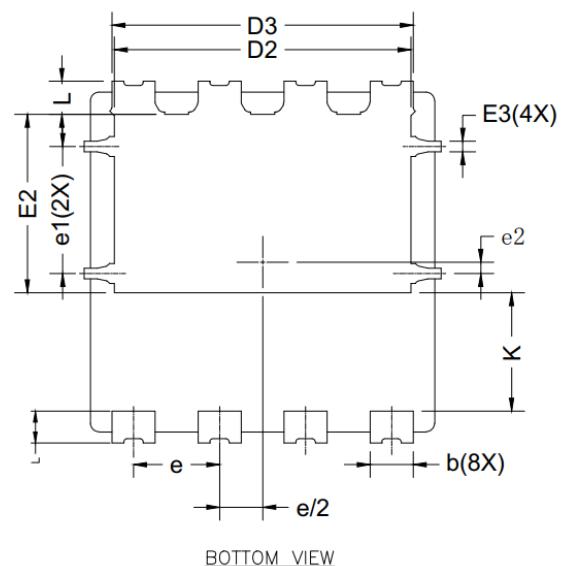
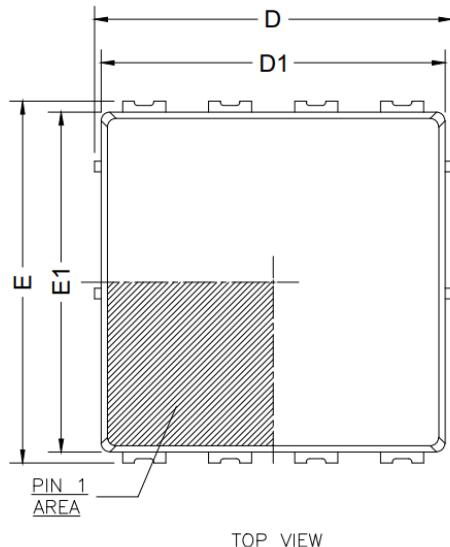


**Figure 15. Peak Diode Recovery dv/dt Test Circuit and Waveforms**



## Package Outlines

## PQFN88



SYMBOL	Common		
	DIMENSIONS MILLIMETER		
	MIN.	NOM.	MAX.
A	0.90	1.00	1.10
A1	0.00	-	0.05
b	0.90	1.00	1.10
c	0.20	0.25	0.30
D	8.20	8.30	8.40
D1	7.90	8.00	8.10
D2	6.80	6.90	7.00
D3	6.90	7.00	7.10
E	8.30	8.40	8.50
E1	7.80	7.90	8.00
E2	4.0450	4.145	4.245
E3	0.15	0.25	0.35
e	2.00 BSC.		
e/2	1.00 BSC.		
e1	2.95 BSC.		
e2	0.265 BSC.		
K	2.68	2.75	2.82
L	0.67	0.77	0.87
L1	0.64	0.74	0.84
θ	0°	-	12°